

# 2020 CMPUG FALL MEETING AGENDA

## NCCAUS – CMPUG Meeting

[www.avsusergroups.org](http://www.avsusergroups.org)

### TOPIC: **Advancements in CMP Applications and Research**

**Meeting Date:** September 1, 2020

**Time:** 10:00 a.m. - 2:00 p.m. (PDT) - [Time Zone Converter](#)

**Platform:** Zoom Webinar (Event Registration Required to Receive Invite)

#### Platinum Sponsors:

- Applied Materials
- Fujimi Corporation
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#### Gold Sponsor:

- KINIK COMPANY

#### Copper Sponsor:

- ADVANCED MATERIALS TECHNOLOGY, INC.

#### CO-CHAIRS

Paul Feeney, Retired, [feeney@rocketmail.com](mailto:feeney@rocketmail.com)

Todd Buley, DuPont, [todd.w.buley@dupont.com](mailto:todd.w.buley@dupont.com)

#### SPEAKERS/AGENDA

10:00 am – Welcome and Acknowledgment of Sponsors: **Co-Chairs Paul Feeney, Todd Buley**

10:05 am – Ultra-rapid Bulk Polishing of 150mm Silicon Carbide Substrate with Single-wafer Chemical Mechanical Planarization (CMP), **Donshan (Sean) Yu, Applied Materials**

10:25 am – Computational modeling of CMP pads: a die-scale model incorporating measured surface roughness, **Brian Salazar, University of California Berkeley**

10:45 am – Enhanced Melt-blown Filtration For Next Generation CMP Slurries and Applications, **Patrick Connor, Pall**

11:05 am – Surface and Electrochemical Evaluations for Barrier and Packaging level CMP Optimization, **G Bahar Basim, University of Florida**

11:25 am – Copper Removal at Short Time with Implications for Polishing Mechanisms, **Len Borucki, Araca**

11:45 am – Break

12:00 pm – CMP defects: Influence of CMP slurry, handling and delivery, **Rahul Trivedi, GlobalFoundries**

12:20 pm – CMP Pad Conditioning and Applications to Soft Pads, **Scott Lawing, Kinik**

12:40 pm – Effective Slurry Mixing and Handling and its Impact on CMP Slurry Particle Health, **Carlo Aparece, Mega Fluids Systems**

01:00 pm – Correlation between dishing/erosion and electrical properties in copper interconnects after chemical mechanical planarization, **Shirley Lin, Versum Materials**

01:20 pm – Correlating Shear Force and CoF to Platen Motor Current in Copper, Cobalt, Tungsten, STI and ILD CMP at Non-steady-state and Steady-state Conditions, **Ara Philipossian, University of Arizona**

01:40 pm – Closing Remarks